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INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application Number	Unknown 10/606 539
(Use as many sheets as necessary)	Filing Date	Even Date Herewith 6-26-03
	First Named Inventor	Ahn, Kie
	Group Art Unit	Unknown 2813
	Examiner Name	Unknown
Sheet 1 of 5	Attorney Docket No: 3	303.533US2

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Substitute for form 1449A/PTO	Complete If Known					
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Applicati n Number	Unknown 10/606539				
	Filing Date	Even Date Herewith 6-26-03				
	First Named Inventor	Ahn, Kie				
	Group Art Unit	Unknown 2813				
	Examiner Name	Unknown				
Sheet 2 of 5	Attorney Docket No: 303.533US2					

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Application Number	Unknown 10 606 539			
	Filing Date	Even Date Herewith 6-26-63			
	First Named Inventor	Ahn, Kie			
	Gr up Art Unit	Unknown 28/3			
	Examiner Name Unknown				
Sheet 3 of 5	Attorney Docket No: 3	303.533US2			

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Substitute for form 1449A/PTO INFORMATION DISCLOSURE	Complete if Known	
STATEMENT BY APPLICANT (Use as many sheets as necessary)	Application Number	Unknown 10/606539
	Filing Date	Even Date Herewith 6-24-03
	First Named Inventor	Ahn, Kie
	Gr up Art Unit	Unknown 2813
	Examiner Name	Unknown
Sheet 4 of 5	Attorney Docket No: 3	303.533U\$2

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